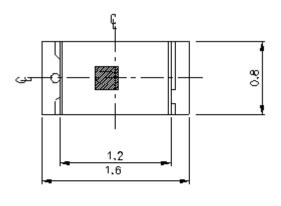
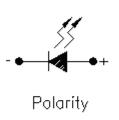
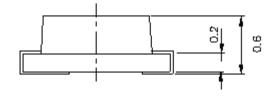


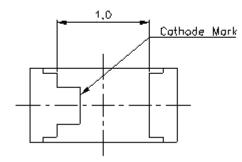
Package Outline Dimensions

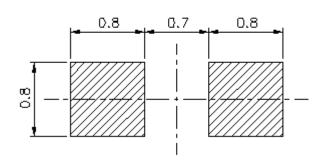






For reflow soldering (Propose)





Note: Tolerances Unless Dimension is ± 0.1 mm ,Unit = mm

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Absolute Maximum Ratings (Ta=25℃)

Parameter	Symbol	Rating	Unit	
Reverse Voltage	V_R	5	V	
Forward Current	I_{F}	25	mA	
Peak Forward Current (Duty 1/10 @1KHz)	I_{FP}	60	mA	
Power Dissipation	Pd	60	mW	
Electrostatic Discharge(HBM)	ESD	2000	V	
Operating Temperature	Topr	-40 ~ +85	$^{\circ}$ C	
Storage Temperature	Tstg	-40 ~ +90	$^{\circ}\mathbb{C}$	
Soldering Temperature	Tsol	Reflow Soldering: 260 °C for 10 sec. Hand Soldering: 350 °C for 3 sec.		

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	Iv	72.0		180	mcd	
Viewing Angle	201/2		120		deg	
Peak Wavelength	λр		632		nm	
Dominant Wavelength	λd	617.5		633.5	nm	I _F =20mA
Spectrum Radiation Bandwidth	Δλ		20		nm	
Forward Voltage	V_{F}	1.75		2.35	V	
Reverse Current	I_R			10	μΑ	V _R =5V

Notes:

- 1.Tolerance of Luminous Intensity ±11 %
- 2.Tolerance of Dominant Wavelength ±1nm
- 3.Tolerance of Forward Voltage ±0.1V

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Bin Range Of Dom. Wavelength

Groups	Bin	Min	Max	Unit	Condition
A	E4	617.5	621.5		1 20 4
	E5	621.5	625.5		
	E6	625.5	629.5	nm	I _F =20mA
	E7	629.5	633.5		

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
Q1	72.0	90.0		
Q2	90.0	112	1	1 20 4
R1	112	140	mcd	$I_F=20mA$
R2	140	180		

Bin Range Of Forward Voltage

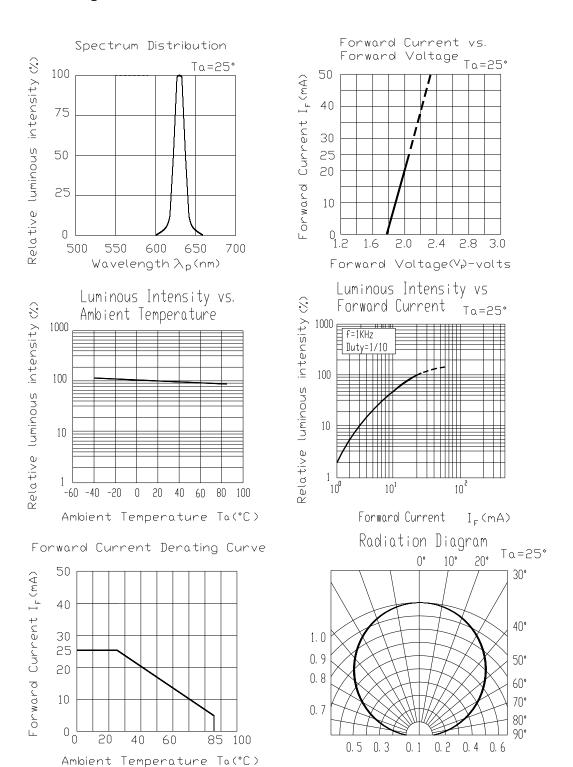
		,				
Groups	Bin	Min	Max	Unit	Condition	
	0	1.75	1.95			
В	1	1.95	2.15	V	I _F =20mA	
	2	2.15	2.35			

Notes:

- 1.Tolerance of Luminous Intensity ±11%
- 2.Tolerance of Dominant Wavelength ±1nm
- 3. Tolerance of Forward Voltage $\pm 0.1 V$

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Typical Electro-Optical Characteristics Curves





Label explanation

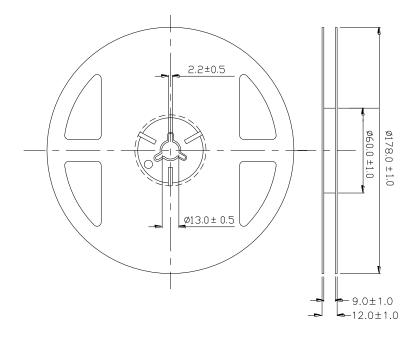
CAT: Luminous Intensity Rank

HUE: Dom. Wavelength Rank

REF: Forward Voltage Rank



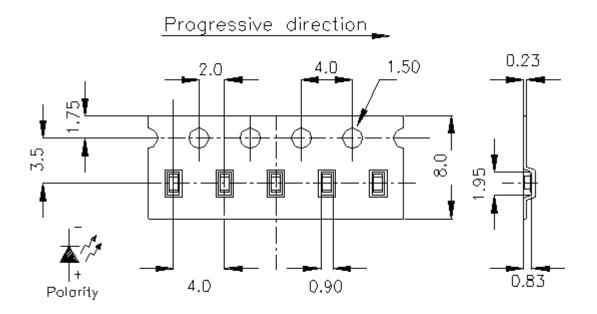
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm.

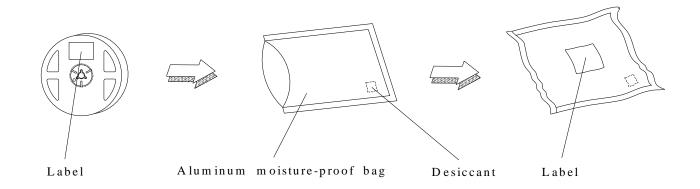


Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging



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Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level: 90%

LTPD: 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260° C $\pm 5^{\circ}$ C Min. 5sec.	6 Min.	22 Pcs.	0/1
2	Temperature Cycle	H:+100°C 15min ∫ 5 min L:-40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H: +100° \subset 5min ∫ 10 sec L: -10° \subset 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°€	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	$I_F = 20 \text{ mA}$	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 Hrs.	22 PCS.	0/1

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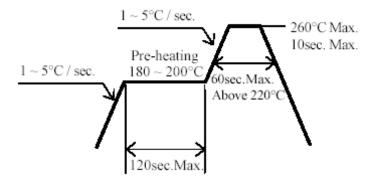


Precautions For Use

- Over-current-proof
 Customer must apply resistors for protection , otherwise slight voltage shift will cause big
- 2. Storage
- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 After opening the package: The LED's floor life is 1 year under 30°C or less and 60% RH or less. If unused LEDs remain, it should be stored in moisture proof packages.
- 2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

 Baking treatment: 60±5℃ for 24 hours.
- 3. Soldering Condition
 - 3.1 Pb-Free solder temperature profile

current change (Burn out will happen).



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

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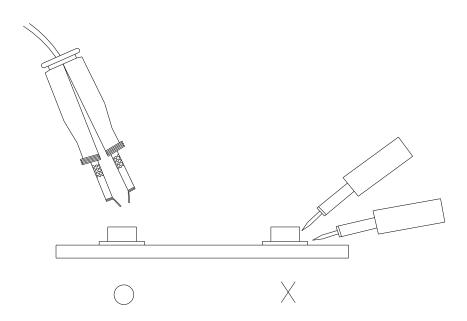


4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5.Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



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